



#874
1-30-03
Hayes

Attorney Ref. 8026-1004

PATENTS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Koki HIRASAWA et al.

Confirmation No. 2347

Serial No. 09/923,394

GROUP 2826

Filed August 8, 2001

Examiner F. Erdem

LEAD FRAME, SEMICONDUCTOR DEVICE
PRODUCED BY USING THE SAME AND
METHOD FOR PRODUCING THE
SEMICONDUCTOR DEVICE

AMENDMENT

Commissioner for Patents

Washington, D.C. 20231

Sir:

Responsive to the Official Action of October 16, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

CANCEL claims 16 and 18.

Amend the claims as follows:

--1. (amended) A lead frame comprising:

a tie bar to which an element loading portion to be loaded with a semiconductor element is connected by a lead forming portion;

RECEIVED
JAN 17 2003
TECHNOLOGY CENTER 2800

ai